

BENEQ P800



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Thin film systems for industrial production

- Production proven
- Batch size up to 8 m²
- Typical dep rate 1–2 μm/24h
- Typical uniformity <2 % over the batch
- Typical materials Al₂O₃, TiO₂, SiO₂
- Typical substrates:
 - Domes
 - High curvature lenses (dia 1...100 mm)
 - Glass wafer or sheet (coating on both sides)
 - Dies on carrier

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PROCESS TYPE

- thermal ALD

USAGE

- production

SUBSTRATE TYPE

- wafers
- glass and metal sheets
- 3D-parts
- Max substrate size:
730x1200 mm

SUBSTRATE LOADING

- manual

MAIN DIMENSIONS

- 3200 × 1340 × 2460 mm

INTEGRATION

- stand-alone

For product inquiries, please contact:

ald-sales@beneq.com

Technical information in this document is subject to change without notice. 3/2021

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